

Adhesive Sheets / Tapes for Electronics Components

# LIOELM TSU™0041SI" Series

# [Characteristics]

Heat-curable adhesive sheets LIOELM TSU0041SI series is designed mainly for FPC applications. Has excellent adhesion to Polyimide / 2-layer CCL / Glass-epoxy / AL / SUS

Once cured, it shows extremely high-heat durability (260°C solder reflow condition)

\* UL authorized

# [Structure]



#### [Technical Data]

			Units	TSU0041SI-25DL	TSU0041SI-35DL
Thickness of Adhesive Sheet				25	35
Thickness of Release Liners	Release liner <sup>①</sup> (Paper)		μm	130	
	Release liner②(PET)			25	
Peel Strength	To PI	Normal	N/10mm	More than 15	More than 15
		After reflow		More than 15	More than 15
	To FR-4	Normal		25	25
		After reflow		CCL broken	CCL broken
	To SUS			20	20
Solder Reflow (260°C peak)			_	Pass	Pass
Solder Floating (260°C×1min.)			_	Pass	Pass

Above data is our self-conducted test result but not our guaranteed performance.

- <Peel strength Measurement Conditions>
- Structure
- : 2-layer CCL / TSU0041SI / Kapton500H (or FR-4)
- Laminating Conditions
- : Laminate  $80^{\circ}C \rightarrow Press 150^{\circ}C \times 2MPa \times 1min. \rightarrow Post Cure 160^{\circ}C \times 1hrs.$
- Peel Speed : 50mm/min.
- Peel Angle : 90°

# [Recommended Lamination Condition]

Vacuum Press at 150°C×2MPa×1min. + Post Cure at 160°C×1hr

# [Notice of Storage Condition]

Please store this product under 10°C / 70%RH refrigerated condition.

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# TOYOCHEM CO., LTD. Information & Communication material Division